Quad 2-Input AND Gate

Description

The MC10H104 is a quad 2-input AND gate. One of the gates has both AND/NAND outputs available. This MECL 10HTM part is a functional/pinout duplication of the standard MECL 10K™ family part, with 100% improvement in propagation delay, and no increase in power-supply current.

Features

- Propagation Delay, 1.0 ns Typical
- Power Dissipation 25 mW/Gate (same as MECL 10K)
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K Compatible
- Pb-Free Packages are Available*



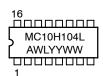
ON Semiconductor®

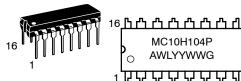
http://onsemi.com

MARKING DIAGRAMS*





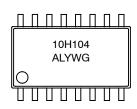




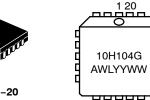
PDIP-16 P SUFFIX **CASE 648**



SOEIAJ-16 **CASE 966**



MC10H104P **AWLYYWWG**





CASE 775

= Assembly Location WL, L = Wafer Lot

YY, Y = Year WW, W = Work Week = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

^{*}For additional marking information, refer to Application Note AND8002/D.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

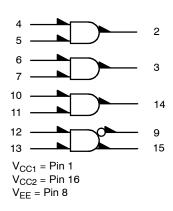
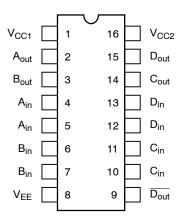


Figure 1. Logic Diagram



Pin assignment is for Dual-in-Line Package.

Figure 2. Pin Assignment

Table 1. MAXIMUM RATINGS

Symbol	Characteristic		Rating	Unit
V _{EE}	Power Supply (V _{CC} = 0)		-8.0 to 0	Vdc
VI	Input Voltage (V _{CC} = 0)		0 to V _{EE}	Vdc
l _{out}	Output Current	Continuous Surge	50 100	mA
T _A	Operating Temperature Range		0 to +75	°C
T _{stg}	Storage Temperature Range	Plastic Ceramic	−55 to +150 −55 to +165	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Table 2. ELECTRICAL CHARACTERISTICS (V_{EE} = -5.2 V \pm 5%) (Note 1)

		0 °		25°		75°		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
Ι _Ε	Power Supply Current	-	39	-	35	-	39	mA
I _{inH}	Input Current High	-	425	-	265	-	265	μΑ
I _{inL}	Input Current Low	0.5	-	0.5	-	0.3	_	μΑ
V _{OH}	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V _{OL}	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
V _{IH}	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V _{IL}	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

^{1.} Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50 Ω resistor to –2.0 V.

Table 3. AC PARAMETERS

		0 °		25°		75°		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
t _{pd}	Propagation Delay	0.4	1.6	0.45	1.75	0.45	1.9	ns
t _r	Rise Time	0.5	1.6	0.5	1.7	0.5	1.8	ns
t _f	Fall Time	0.5	1.6	0.5	1.7	0.5	1.8	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

ORDERING INFORMATION

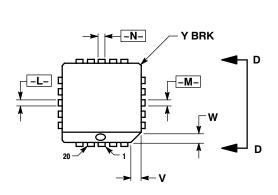
Device	Package	Shipping [†]
MC10H104M	SOEIAJ-16	50 Unit / Rail
MC10H104MG	SOEIAJ-16 (Pb-Free)	50 Unit / Rail
MC10H104MEL	SOEIAJ-16	2000 / Tape & Reel
MC10H104MELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel
MC10H104FN	PLLC-20	46 Units / Rail
MC10H104FNG	PLLC-20 (Pb-Free)	46 Units / Rail
MC10H104FNR2	PLLC-20	500 / Tape & Reel
MC10H104FNR2G	PLLC-20 (Pb-Free)	500 / Tape & Reel
MC10H104L	CDIP-16	25 Unit / Rail
MC10H104P	PDIP-16	25 Unit / Rail
MC10H104PG	PDIP-16 (Pb-Free)	25 Unit / Rail

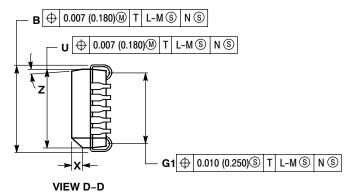
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

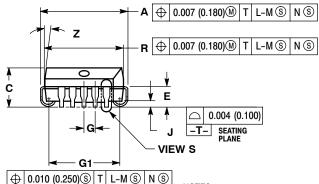
PACKAGE DIMENSIONS

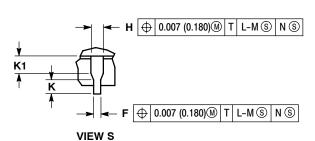
20 LEAD PLLC CASE 775-02

ISSUE E









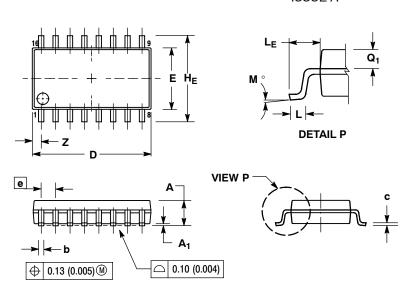
- NOTES:
 1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. DIMENSIONS IN INCHES.
 3. DATUMS -L., -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

- PARTING LINE.
 4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM —T-, SEATING PLANE.
 5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- PLASTIC BODY.
 7. DIMENSION H DOES NOT INCLUDE DAMBAR DIMIENSION H DUES NOT INCLUDE DAMBAR
 PROTRUSION OR INTRUSION. THE DAMBAR
 PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION
 TO BE GREATER THAN 0.037 (0.940). THE DAMBAR
 INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO
 BE SMALLER THAN 0.025 (0.635).

	INC	INCHES MILLIN		IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Χ	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

PACKAGE DIMENSIONS

SOEIAJ-16 CASE 966-01 **ISSUE A**

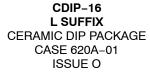


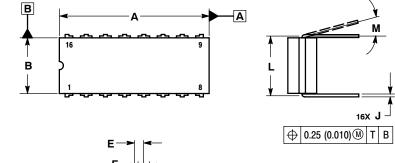
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI

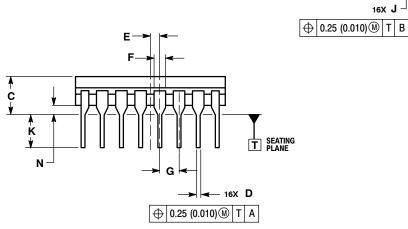
- NOTES:

 1 DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS DI AND E DO NOT INCLUDE MOLD
 FLASH OR PROTRUSIONS AND ARE MEASURED
 AT THE PARTING LINE. MOLD FLASH OR
 PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006)
 PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT
 INCLUDE DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08 (0.003)
 TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 DAMBAR CANNOT BE LOCATED ON THE LOWER
 RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT LEAD
 TO BE 0.46 (0.018).

	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050	BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10°
Qī	0.70	0.90	0.028	0.035
Z		0.78		0.031







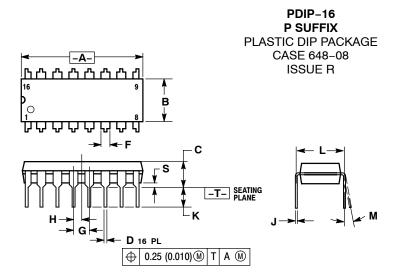
NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION LTO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.
- BODY. THIS DRAWING REPLACES OBSOLETE CASE OUTLINE 620-10.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.750	0.785	19.05	19.93
В	0.240	0.295	6.10	7.49
C		0.200		5.08
D	0.015	0.020	0.39	0.50
Е	0.050	BSC	1.27	BSC
F	0.055	0.065	1.40	1.65
G	0.100	0.100 BSC		BSC
Н	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300	BSC	7.62 BSC	
M	0 °	15°	0 °	15°
N	0.020	0.040	0.51	1.01

PACKAGE DIMENSIONS



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982
- CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETER	
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
Н	0.050 BSC		1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10 °
S	0.020	0.040	0.51	1.01

MECL 10H and MECL 10K are trademarks of Motorola, Inc.

ON Semiconductor and 📖 are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082-1312 USA Phone: 480-829-7710 or 800-344-3860 Toll Free USA/Canada Fax: 480-829-7709 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free

Japan: ON Semiconductor, Japan Customer Focus Center 2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051 Phone: 81-3-5773-3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative

MC10H104/D